

WLAN 802.11 b/g/n and Bluetooth® v2.1 + EDR Module

FEATURES

- IEEE 802.11 b/g/n Compliant
- Typical WLAN Transmit power:
 - +20dBm, 11Mbps, CCK (b)
 - +14.5dBm, 54Mbps, OFDM (g)
 - +12.5dBm, 65Mbps, OFDM (n)
- · Typical WLAN Receiver sensitivity:
 - -89dBm, 8% PER, 11Mbps
 - -76dBm, 10% PER, 54Mbps
 - -73dBm, 10% PER, 65Mbps
- Bluetooth v2.1 + Enhanced Data Rate (EDR)
- Increased Bluetooth Transmit Power: +9.5dBm Typical
- -92dBm typical Bluetooth® Receiver Sensitivity
- Best-In-Class WLAN and Bluetooth Coexistence Technology on a Single-Chip
- Enhanced Low Power (ELP™) Technology for Extended Battery Life
- On Board TCXO, Power Regulation and U.FL Antenna Connector
- Hardware and Software Pre-integration With TI's AM/DM37x (ARM Cortex[™]-A8), AM18xx (ARM9), and OMAP4[™] (ARM Cortex[™]-A9) Platforms
- Software Upgradable for ANT and Bluetooth Low Energy
- Dimensions: 13mm x 18mm x 1.9mm
- FCC/IC/CE Certified
- Operating Temperature Range: –40°C to 85°C

APPLICATIONS

- Consumer Devices
- Industrial and Home Automation
- Point of Sale and Point of Purchase
- Video Conferencing, Video Camera and VolP
- Medical Devices
- · Security and Surveillance

DESCRIPTION

The following product brief applies to LS Research's WLAN + *Bluetooth* module, series name: TiWi. The WLAN + *Bluetooth* chip used is the WL1271 from Texas Instruments.

WL1271-TiWi is a fully-integrated performance module offered by LS Research using TI's single-chip WL1271 2.4GHz IEEE 802.11 b/g/n and Bluetooth v2.1 + Enhanced Data Rate (EDR) Transceiver. Based on TI's 6th generation WLAN technology and 7th generation *Bluetooth* technology, the solution provides best-in-class coexistence capabilities coupled with TI's Enhanced Low Power (ELP) technology. The WL1271-TiWi is provided as a module to help customers reduce development time, lower manufacturing costs, save board space, ease certification, and minimize RF expertise required. For evaluation and development, various platforms are available which integrate the WL1271-TiWi module, Linux WLAN drivers, BlueZ Bluetooth stack, and sample source applications running on a TI host processor (AM/DM37x, AM18x, OMAP4).

The full specification and purchasing of the WL1271-TiWi module can be found on LSR's website (www.lsr.com/tiwi). More information on TI's wireless platform solutions can be found on the Wireless Connectivity Wiki (www.ti.com/connectivitywiki).

Disclaimer:

All content in and linked to this product brief is provided by TI "AS IS" without express or implied warranties of any kind, and it may contain errors, omissions and technical inaccuracies. TI does not endorse or warrant any of the third party products or services referenced on this product brief. This information is provided subject to TI's Terms of Use.

Be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

OMAP4 is a trademark of Texas Instruments.

Cortex is a trademark of ARM.

Bluetooth is a registered trademark of Bluetooth SIG, Inc. All other trademarks are the property of their respective owners.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

TI E2E Community Home Page

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated

e2e.ti.com